

Reliability Test Standards

(1) Section A:

- 1. Molded Power Inductor
- 2. Ferrite Chip Beads and Inductor
- 3. LAN Transformer
- 4. SMD Power Inductor SPS2520 & SPS2016
- 5. Ceramic Wirewound Inductor (SCI Series)
- → Table 1 (Automotive)
- (2) Section B:
 - 6. HF Transformer
 - 7. Standard Power Inductor
 - 8. Wireless Charging
 - 9. Toroidal Choke Coil
- → Table 2 (Automotive)
- (3) For other products not in the list, we shall handle it on a case-by-case basis.

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Section A

- 1. Molded Power Inductor
- 2. Ferrite Chip Beads and Inductor
- 3. LAN Transformer
- 4. SPS2520 and SPS2016
- 5. Ceramic Wirewound Inductor (SCI Series)
- → Table 1 (Automotive)



Test	Failure Criteria	Test Condition
Pre and Post-Stress Electrical Test	a. Follow product data sheet	a. Sample Size: 77pcs b. Equipment: LCR Meter OHM Meter
High Temperature Exposure (Storage) (AEC-Q200)	 a. Appearance: No damage. b. Impedance change: within±15% of initial value c. Inductance change: within±10% of initial value d. Q value: No out of spec e. RDC change: within ±15% of initial value and no out of spec 	 a. Pre-condition: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profile) (Sample Size: 77pcs) b. Temperature: Refer datasheet c. Duration: 1000 hours min (measurement at 250 and 500 hrs) d. Place the parts at room temperature for 24±2 hrs and then measured the electrical characteristic. e. Equipment: LCR Meter & OHM Meter & microscope
Temperature Cycling (AEC-Q200)	 a. Appearance: No damage. b. Impedance change: within±15% of initial value c. Inductance change: within±10% of initial value d. Q value: No out of spec e. RDC change: within ±15% of initial value and no out of spec 	 a. Pre-condition: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profile) (Sample Size: 77pcs) b. Highest Temperature & Lowest Temperature: Follow datasheet c. Maintain the predetermined temperature at least 30 mins. Rise to highest temperature within 1 min and maintain for at least 30 mins. Drop to lowest temperature within 1 min. Cycle, 1000 times. d. Place the parts at room temperature for 24±2 hrs and then measured the electrical characteristic. e. Equipment: LCR Meter & OHM Meter & microscope



Test	Failure Criteria	Test Condition
Destructive Physical Analysis	NA	NA
Biased Humidity (AEC-Q200)	 a. Appearance: No damage. b. Impedance change: within±15% of initial value c. Inductance change: within±10% of initial value d. Q value: No out of spec e. RDC change: within ±15% of initial value and no out of spec 	 a. Pre-condition: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profile) (Sample Size: 77pcs) b. Humidity: 85±3% R.H c. Temperature: 85±2 °C d. Duration: 1000 hours min e. Place the parts at room temperature for 24±2 hrs and then measured the electrical characteristic. f. Equipment: LCR Meter & OHM Meter & microscope
Operational Life (High temperature loading) (AEC-Q200)	 a. Appearance: No damage. b. Impedance change: within±15% of initial value c. Inductance change: within±10% of initial value d. Q value: No out of spec e. RDC change: within ±15% of initial value and no out of spec 	 a. Pre-condition: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profile) (Sample Size: 77pcs) b. Temperature: Refer datasheet c. Duration: 1000hrs min. with 100% rated current. d. Place the parts at room temperature for 24±2 hrs and then measured the electrical characteristic. e. Equipment: LCR Meter & OHM Meter & microscope
Appearance	a. Appearance: No damage.	a. Inspect outer appearance, body marking and workmanship without electrical test.b. Equipment: Microscope



Test	Failure Criteria	Test Condition
Dimension	a. Follow Dimension Spec in datasheet	a. Refer datasheetb. Sample Size: 30pcsc. Equipment: Caliper
Terminal Strength	a. Appearance: No damage.	 a. Apply 910g pull force for 5~10 secs to the pin terminal. b. Sample Size: 30pcs c. Equipment: Microscope
Resistance to Solvents	a. Appearance: No damage.	a. Add aqueous wash chemical - OKEM to clean or equivalent.b. Sample Size: 5pcsc. Equipment: Microscope
Mechanical Shock	a. Appearance: No damage. b. Impedance change: within±15% of initial value c. Inductance change: within±10% of initial value d. Q value: No out of spec e. RDC change: within ±15% of initial value and no out of spec.	a. Pre-condition: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profile) (Sample Size: 30pcs) Type Peak value Normal duration (g's) (D) (ms) Waveform Velocity change (Vi)fif/sec (Vi)fif/sec 12.3 Lead 100 6 Half-sine 12.3 b. Equipment: LCR Meter & OHM Meter & microscope
Vibration	a. Appearance: No damage. b. Impedance change: within±15% of initial value c. Inductance change: within±10% of initial value d. Q value: No out of spec e. RDC change: within ±15% of initial value and no out of spec	 a. Pre-condition: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profile) (Sample Size: 30pcs) b. Equipment: Vibration Checker, LCR Meter & OHM Meter & Microscope
		 c. Total Amplitude:5g d. Oscillation Frequency: 10HZ~2KHZ~10Hz for 20 minutes. e. Testing Duration: 12 hours (20 minutes, 12 cycles each of 3 orientations)

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Test	Failure Criteria	Test Condition
Resistance to Soldering	a. Appearance: No damage.	a. Sample Size: 30pcs
Heat	 b. Impedance change: within±15% of initial value c. Inductance change: within±10% of initial value d. Q value: No out of spec e. RDC change: within ±15% of initial value and no out of spec 	Soldering Temperature(*C) Time(s) Temperature ramp/immersion and emersion rate 260 ±5 10 ±1 25mm/s ±6 mm/s 1 b. Equipment: LCR Meter & OHM Meter & 50X CCD
Thermal shock (AEC-Q200)	a. Appearance: No damage. b. Impedance change: within±15% of initial value c. Inductance change: within±10% of initial value d. Q value: No out of spec e. RDC change: within ±15% of initial value and no out of spec	 a. Pre-condition: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profile) (Sample Size: 30pcs) b. Highest Temperature & Lowest Temperature: Follow datasheet c. Maintain the low temperature for 15±1 mins. When the temperature hit the predetermined temperature, Rise to highest temperature within 20 secs for 15±1 mins. Number of cycles is 300. d. Place the parts at room temperature for 24±2 hrs and then measured the electrical characteristic. e. Equipment: Thermal shock tester, LCR Meter & OHM Meter
ESD	a. Appearance: No damage.	a. Sample Size: 15pcs b. Equipment: microscope

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Test	Failure Criteria	Test Condition
Solderability	a. Appearance: More than 95% of the terminal electrode shall be covered with solder.	 a. Sample Size: 15pcs b. Method B: Baking: 155±5°C 4 Hours; Soldering Temp: 235±5°C; Soldering Time: 5 + 0/-0.5S; Depth: completely cover the termination.
		 c. Method D: Steam aging: (93±3°C, 8 hours±15 min) Soldering Temp: 260±5°C Soldering Time: 30 + 0/-0.5 sec Depth: completely cover the termination. Remarks: Perform soldering until solder is formed on the terminations. All terminations shall have visible solder residues. d. Equipment: Solder Pot & 50X CCD
Electrical Characteristics	a. Follow datasheet	 a. Sample Size: 30pcs / lot b. Lots: 3 lots c. Equipment: LCR Meter & OHM Meter d. Record min, max, mean and standard deviation of electrical characteristics.
Flammability	a. Not required electrical test	a. Sample Size: 30pcsb. V-0 or V-1 are acceptable.



Test	Failure Criteria	Test Condition
Board Flex	a. Appearance: No damage.	a. Pre-condition: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profile) (Sample Size: 30pcs)
		b. Place the component (facing down) on the 100mm X 40mm board.
		c. Apply force to bend the board until D, 2mm min for 60 + 5 sec for 1 time. Support Solder Chip Printed circuit board before testing
		45+2 A5+2 RECOTI2-M
		Printed circuit board under test Displacement
		d. Equipment: Microscope
Terminal Strength (SMD)	a. Appearance: No damage.	a. Pre-condition: Run through IR reflow for 2 times. (IPC/JEDEC J-STD-020D Classification Reflow Profile) (Sample Size: 30pcs)
		b. Apply 17.7 N (1.8 Kg) force gradually to the side of PCBA device for 60 +1 secs without apply shock to the component.
		radius 0,5 mm DUT wide substrate press tool
		c. Equipment: Microscope



Section B

- 1. HF Transformer
- 2. Standard Power Inductor
- 3. Wireless Charging
- 4. Toroidal Choke Coil
- → Table 2 (Automotive)



Table 2- Reliability Test Standard (Automotive)

Test	Failure Criteria	Test Condition
High Temperature Exposure (Storage) (AEC-Q200)	a. MIL-STD-202 b. Method 108	 a. Sample Size: 77pcs b. 1000 hrs. at rated operating temperature (e.g. part can be stored for 1000 hrs. @ 125°C, 105°C and 85°C.) c. Measured the electrical characteristic within 24±2 hrs after the test. *The actual test temperature follow customer requirements.
Temperature Cycling (AEC-Q200)	a. JESD22 Method b. JA-104	 a. Sample Size: 77pcs b. Method: -40 ± 2°C 30mins Min. Transition time, 1min Max. 125°C ± 2°C 30min Min. Transition time, 1min Max. Number of cycles: 1000
Biased Humidity (AEC-Q200)	a. MIL-STD-202 b. Method 103	a. Sample Size: 77pcs b. Humidity: 85 ± 3% RH c. Temperature: 85°C± 2°C d. Duration: 1000 hours
Appearance	a. MIL-STD-883 b. Method 2009	a. Sample Size: All submitted qty b. Inspect equipment, marking and workmanship c. not required electrical test
Dimension	a. JESD22 Method b. JB-100	a. Sample Size: All submitted qtyb. Verify dimensionc. not required electrical test of user and manufacturer.
Resistance to Solvents (AEC-Q200)	a. MIL-STD-202 b. Method 215	 a. Sample Size: 5pcs b. Immerse in solvent, 3+0.5/-0 mins at 25±5°C. Brush 10 times by using toothbrush, repeat 3 times and rinse with water, dry by air blow.

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Test	Failure Criteria	Test Condition
Vibration Test (Component)	a. MIL-STD-202 b. Method 204	 a. Sample Size: 30pcs b. Frequency range: 10 Hz - 2000 Hz -10 Hz for 20 minutes (1 cycle) c. 12 cycles for each orientation and a total of 12 hours d. Maximum acceleration (m / s2): 5G, Noload Amplitude range: 1.52mm
Solderability	a. Appearance: More than 95% of the terminal electrode shall be covered with solder. (J-STD-002)	 a. Sample Size: 15pcs b. Method: Steam aging: (93±3°C, 16 hours±30 min) Soldering Temp: 245±5°C Soldering Time: 5 + 0/-0.5 sec
Electrical Characteristics	a. Follow datasheet	 a. Sample Size: All submitted qty b. Record min, max, mean and standard deviation of electrical characteristics as per lot and sampling size requirements.
Pre & Post Stress Electrical Test	a. Follow datasheet	a. Test is performed at 25±5°C except applicable stress reference and the additional requirements
Drop Test (Packaging)	a. ASTM D5276 – 98	a. Use drop tester to drop the part in carton box from 1m height.b. Test sequence: Corner, three sides, six surfaces.
Salt spray test	a. GB2423.17-2008	a. Salt water (5% NaCl) solution b. PH value 6.6-7.2 c. Temperature 35±3°C d. Humidity: 95-98% RH e. Duration: 24Hrs



For other products not in the list, we shall handle it on a case-by-case basis.

→ Please consult the Engineering/Quality Managerial teams for applicable reliability test requirements.

